

Ultra-small 14.6 m Ω 1.0 A GreenFET Load Switch with Discharge and Reverse Blocking

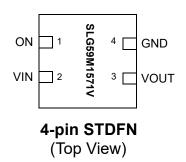
General Description

The SLG59M1571V is designed for load switching applications. The part comes with one 14.6 m Ω 1.0 A rated MOSFET with Reverse Blocking and is controlled by a single ON control pin. The product is packaged in an ultra-small 1.0 x 1.0 mm package.

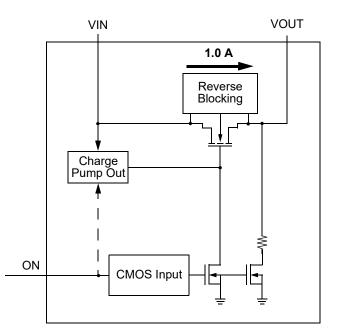
Features

- One 14.6 m Ω 1.0 A MOSFET
- Reverse Blocking
- V_{IN} = 0.85 V to 1.9 V
- One integrated VGS Charge Pump
- · Integrated Discharge Resistor
- Over Temperature Protection
- Pb-Free / Halogen-Free / RoHS compliant
- STDFN 4L, 1.0 x 1.0 x 0.55 mm

Pin Configuration



Block Diagram





Pin Description

Pin #	Pin Name	Туре	Pin Description
1	ON	Input	Turns on MOSFET.
2	VIN	MOSFET	Power Input MOSFET
3	VOUT	MOSFET	Power Output MOSFET
4	GND	GND	Ground

Ordering Information

Part Number	Туре	Production Flow
SLG59M1571V	STDFN 4L	Industrial, -40 °C to 85 °C
SLG59M1571VTR	STDFN 4L (Tape and Reel)	Industrial, -40 °C to 85 °C



SLG59M1571V

Absolute Maximum Ratings

Parameter	Description	Conditions	Min.	Тур.	Max.	Unit
V _{IN}	Power Supply			-	2.5	V
T _S	Storage Temperature		-65		150	°C
ESD _{HBM}	ESD Protection	Human Body Model	2000	-		V
W _{DIS}	Package Power Dissipation			-	0.5	W
MOSFET IDS _{PK}	Peak Current from Drain to Source	For no more than 1 ms with 1% duty cycle			1.5	А
Note: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating						

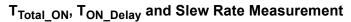
only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

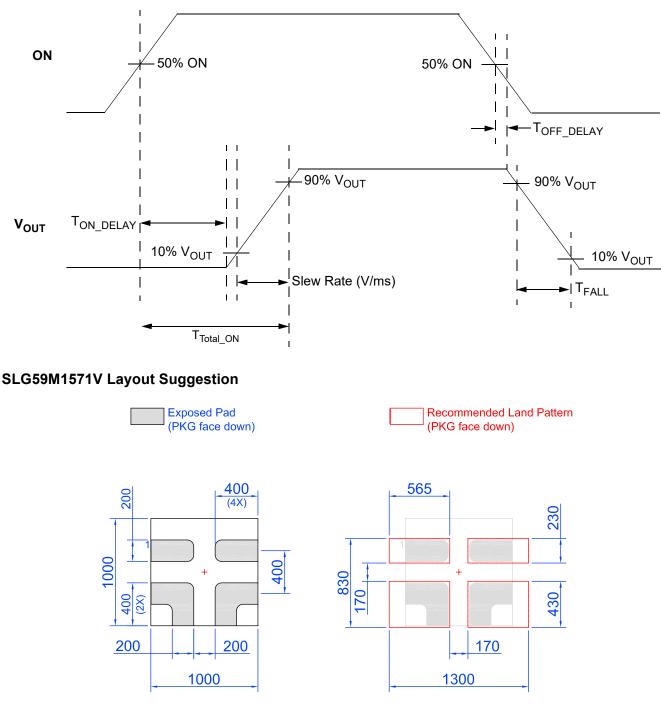
Electrical Characteristics

 T_A = -40 °C to 85 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Тур.	Max.	Unit
V _{IN}	Power Supply Voltage	-40 °C to 85 °C	0.85		1.9	V
I	Device Supply Current (DIN 2)	when OFF, VOUT = 1.9 V		0.4	3	μA
I _{DD}	Power Supply Current (PIN 2)	when ON, No load		27	40	μA
I _{REV_LKG}	Reverse Leakage Measured from Pin3 to Pin2	when OFF, VOUT = 1.9 V, VIN = 0 V		1.1	4	μA
RDS _{ON}	Static Drain to Source	T _A 25°C MOSFET		14.6	17	mΩ
ND3 _{ON}	ON Resistance	T _A 85°C MOSFET		17.2	20	mΩ
IDS	Operating Current	V _D = 0.85 V to 1.9 V			1.0	Α
T _{ON_Delay}	ON pin Delay Time	50% ON to Ramp Begin V_{IN} = 1.2 V, Source_Cap = 10 μ F, R_L = 20 Ω		90	200	μs
T _{Total_ON}	Total Turn On Time	V_{IN} = 1.2 V, Source_Cap = 10 µF, R _L = 20 Ω		310	500	μs
T _{SLEWRATE}	Slew Rate	V_{IN} = 1.2 V, Source_Cap = 10 µF, R _L = 20 Ω		4.7		V/ms
Р	Discharge Registeres	Full Operating Range	50		120	Ω
R _{DIS}	Discharge Resistance	V _{IN} = 1.2 V @ -40 °C to 85 °C	54	67	80	Ω
ON_V _{IH}	Initial Turn On Voltage	Internal Charge Pump ON	0.85		VD	V
ON_V_{IL}	Low Input Voltage on ON pin	Internal Charge Pump OFF	-0.3	0	0.3	V
ON_R	Input Impedance on ON pin		100			MΩ
THERMON	Thermal shutoff turn-on temperature			120		°C
THERMOFF	Thermal shutoff turn-off temperature			100		°C
THERM	Thermal shutoff time				1	ms
T _{Delay_OFF}	OFF Delay Time	50% ON to V_S Fall, V_IN = 1.2 V, R_L = 20 Ω		12	16	μs



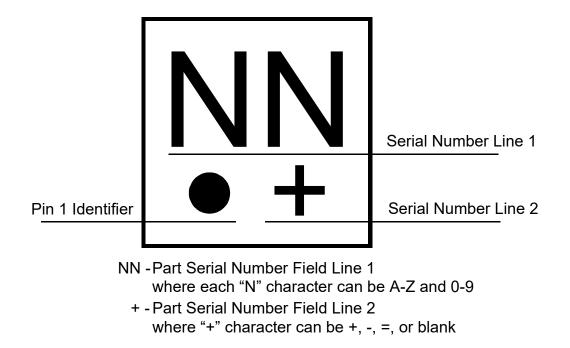




Note: All dimensions shown in micrometers (µm)



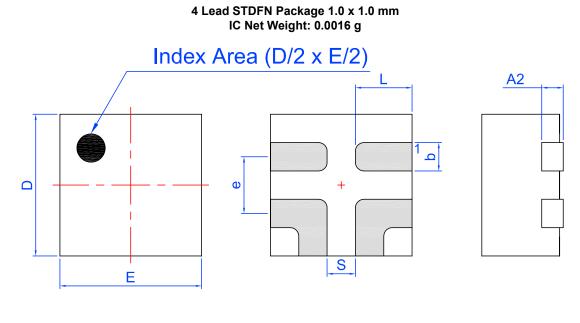
Package Top Marking System Definition

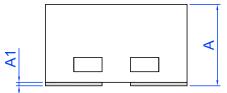




SLG59M1571V

Package Drawing and Dimensions





Unit: mn	า						
Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	0.95	1.00	1.05
A1	0.005	-	0.060	E	0.95	1.00	1.05
A2	0.10	0.15	0.20	L	0.35	0.40	0.45
b	0.15 0.20 0.25			S	(0.2 REF	
е	().40 BSC	;				

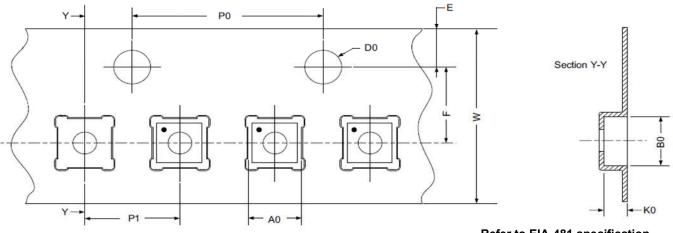


Tape and Reel Specifications

Dookogo	# of	Nominal	Max	Units	Reel &	Leade	r (min)	Trailer (min)		nin) Tape		
Package Type	# of Pins	Package Size [mm]	per Reel	per Box	er Box [mm]		Pockets	Length [mm]	Pockets	Length [mm]		Pitch [mm]
STDFN 4L Green	4	1.0 x 1.0 x 0.55	8000	8000	178 / 60	200	400	200	400	8	2	

Carrier Tape Drawing and Dimensions

Package Type	PocketBTM Length	PocketBTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge		Tape Width
	A0	В0	K0	P0	P1	D0	E	F	w
STDFN 4L Green	1.16	1.16	0.63	4	2	1.5	1.75	3.5	8



Refer to EIA-481 specification

Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 0.55 mm³ (nominal). More information can be found at www.jedec.org.



Revision History

Date	Version	Change
2/14/2022	1.02	Renesas rebranding Fixed typos
11/20/2017	1.01	Updated Package Marking Definition Updated Layout Suggestion

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